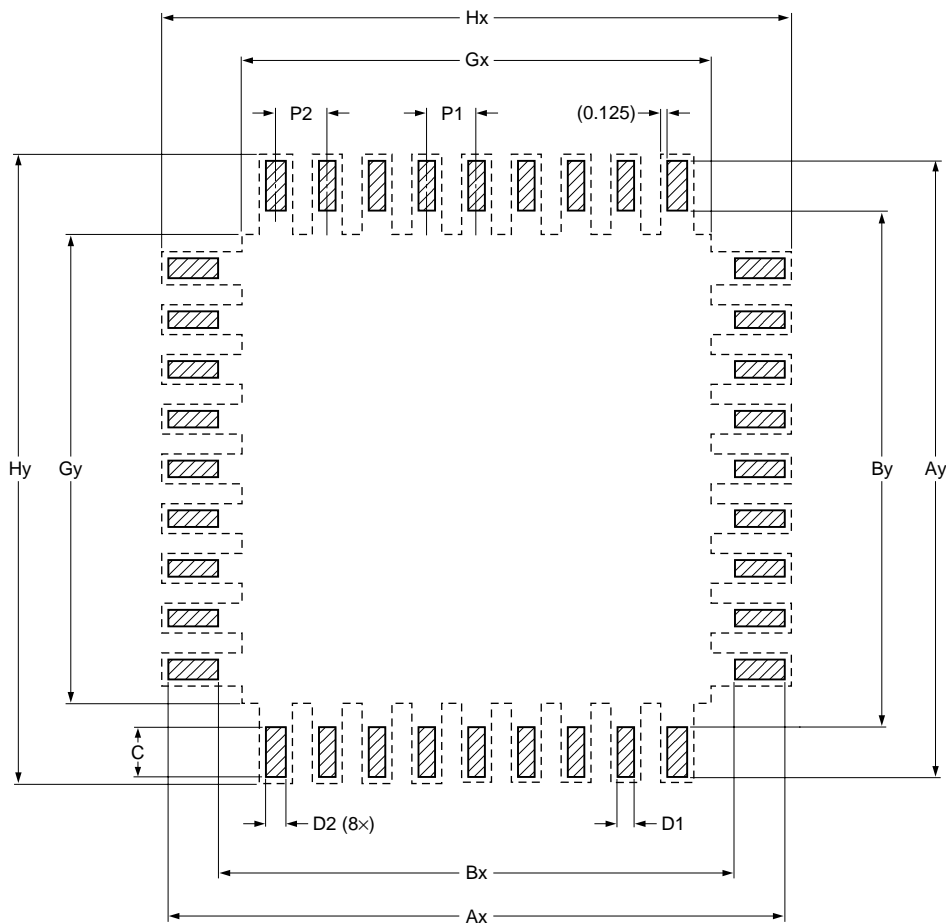



Footprint information for reflow soldering of QFP64 package

SOT319-2



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
1.000	1.050	25.300	19.300	20.900	14.900	2.200	0.600	0.700	20.500	14.500	25.550	19.550